3.2x1.6mm SMD CHIP LED LAMP

APC3216SECK SUPER BRIGHT ORANGE

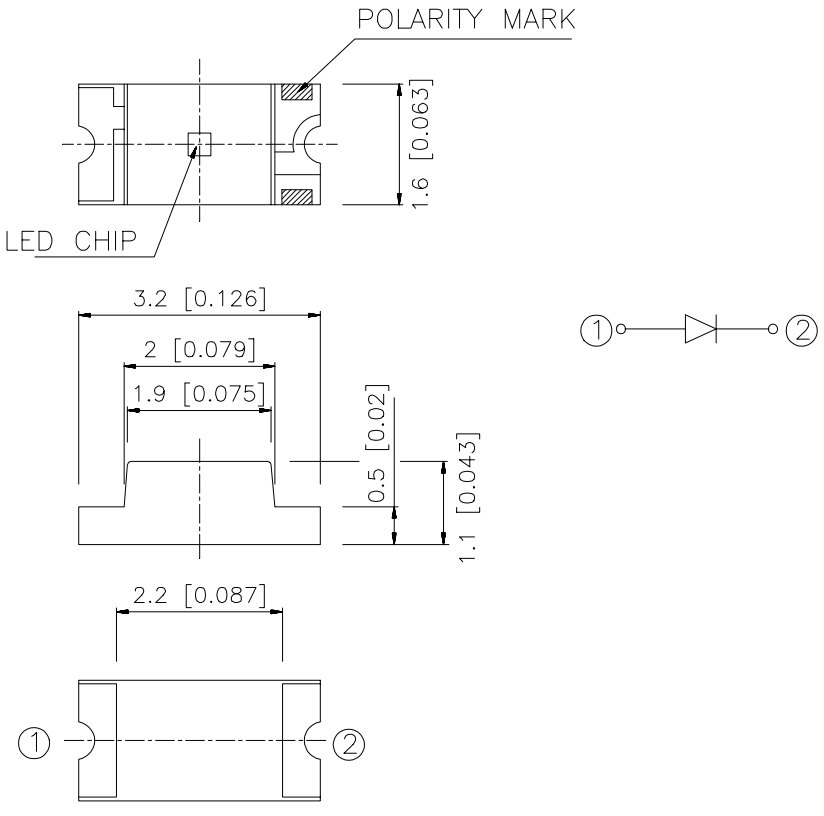
Features

- 3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Super Bright Orange source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.0079") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APC3216SECK	SUPER BRIGHT ORANGE (InGaAlP)	WATER CLEAR	50	160	120°

Note:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

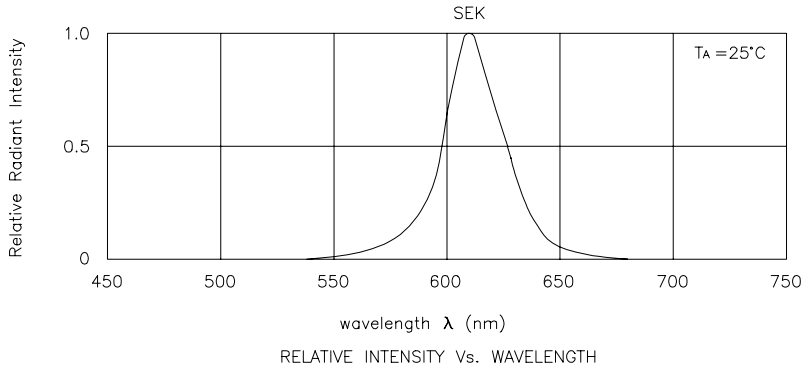
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	I_F=20mA
λD	Dominate Wavelength	Super Bright Orange	601		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	I_F=20mA
C	Capacitance	Super Bright Orange	15		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Super Bright Orange	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Super Bright Orange		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

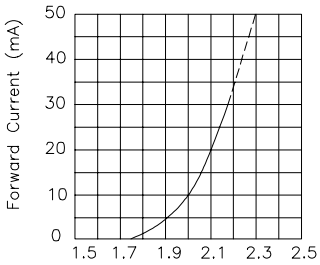
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

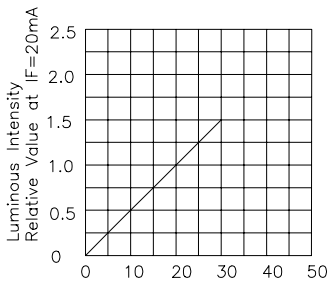


RELATIVE INTENSITY Vs. WAVELENGTH

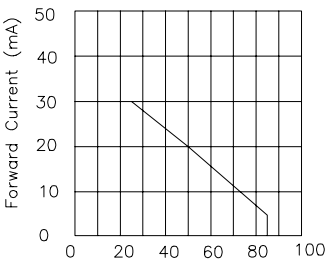
Super Bright Orange APC3216SECK



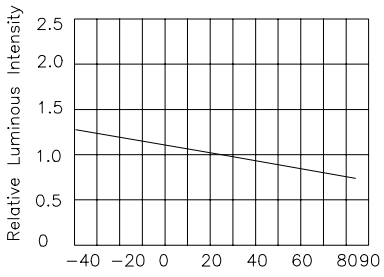
FORWARD CURRENT Vs.
FORWARD VOLTAGE



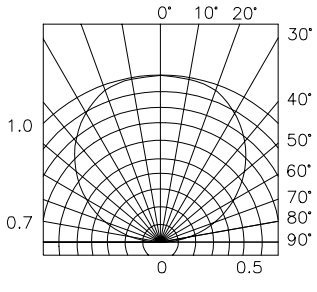
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

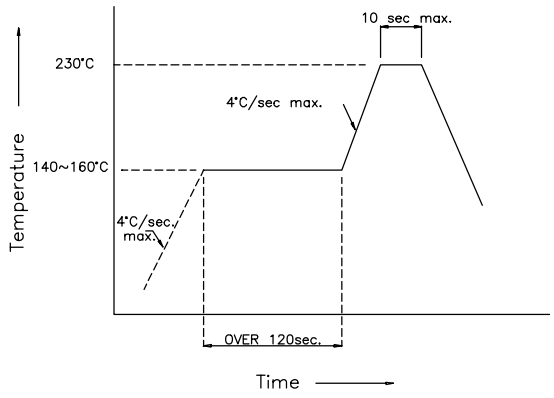


SPATIAL DISTRIBUTION

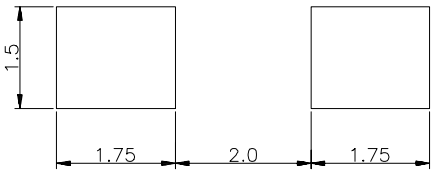
APC3216SECK

SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern
(Units : mm)



Tape Specifications
(Units : mm)

